



At Palmetto Adhesives Company, we understand that industries are constantly evolving. Our team works hard to stay at the forefront of the adhesives industry with products that are innovative, environmentally-safe, and performance driven. Whether your system utilizes extrusion, roll-on, spray, or another application method, our adhesives are formulated to provide efficient and dependable results. Our experienced technicians are also capable of developing custom products to meet your specific application needs. For more information about any of our products, contact Palmetto Adhesives today. We can help you select the adhesive that is best suited to your production specifications.



For more information contact us at  
**800.572.5403**



[www.palmettoadhesives.com](http://www.palmettoadhesives.com)



## **PINNACLE/BOND**

PinnacleBond packaging adhesives offer a versatile choice for bonding a wide range of coated and uncoated corrugated and chipboard stocks designed for the food packaging industry. As our largest moving hot melt adhesives, these metallocene-based adhesives perform well in multiple applications and run smoothly on the high-speed packaging lines used in food, beverage, and other industries. PinnacleBond is an excellent general purpose packaging adhesive that offers superior performance in a wide range of applications.

 **Hot Melt**

## PINNACLEBOND TECHNOLOGY

The PinnacleBond series of adhesives are the highest performing packaging adhesives in our brands. PinnacleBond offers clean delivery and remarkable bonding that translate to significant savings for you. Experience the benefits of PinnacleBond.

- No char or gel will form to plug the tank or glue tips—no downtime, less maintenance
- No stringing means less clean-up
- Precise bead size and placement, less difficulty, and less adhesive is required to get the job done right
- Consistent viscosity allows for trouble-free packaging runs
- Extreme heat or cold—PinnacleBond adhesives perform



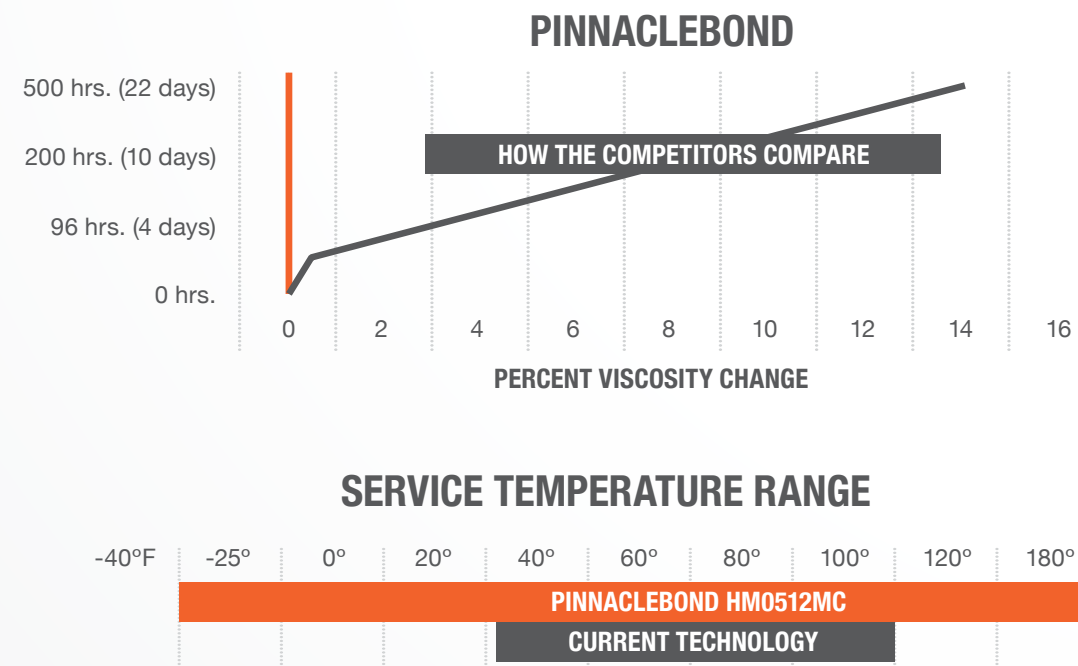
## PINNACLEBOND INTEGRITY

PinnacleBond high performance adhesives deliver precise and reliable bead placement that will not string or damage packaging, and the hot melt dries to a light, white color. Your PinnacleBond sealed package will not pop open—whether in subzero or scorching conditions. Also, PinnacleBond adhesives are odor-free and easily removed, creating a more sustainable environment.

## PINNACLEBOND VALUE

The superior technology in PinnacleBond adhesives means better, cleaner, more flexible performance using less product. The ultimate benefit is measurable as savings to you.

- PinnacleBond adhesives' clean consistent machining reduces maintenance, repair and parts replacement
- Stronger bonds with less adhesive means greater mileage
- Adhesive performance from -40 to 180°F on a broad array of substrates makes PinnacleBond hot melt the only adhesive for your packaging application



## BENEFITS

- ▴ Lowers adhesive costs as much as 15 to 30%
- ▴ Reduced downtime. Eliminates unscheduled maintenance
- ▴ No adhesive build up on equipment
- ▴ No odor. No smoke. Provides for user friendly work environment
- ▴ Enhances packaging appearance
- ▴ No viscosity gain over a 500 hour pot life, allowing for control of bead placement and bead size
- ▴ No plugged nozzles and hoses with increased mileage
- ▴ Resists extreme heat and cold

## FEATURES

- ▴ Increased Mileage
- ▴ No Stringing or Tailing, Clean Machining
- ▴ Odor Free
- ▴ Light in Color
- ▴ Superior Thermal Stability
- ▴ Eliminates Char and Gel
- ▴ Wide Service Range

*Let's Stick Together*



PROPERTY	HM0421MC	HM0512MC	HM0721MC	HM5277MC	HM0975MC	HM0955MC
Type	High performance, low application temperature hot melt adhesive designed with good cold and heat resistance	High speed, freezer grade adhesive designed with good cold and heat resistance	High tack general purpose adhesive designed with good cold and heat resistance	High performance, extreme high heat resistant adhesive designed for fast line speeds	High performance, high heat resistant adhesive designed for fast line speeds	High performance, slow setting adhesive designed to adhere difficult to bond substrates
Recommended Application Temperature	250 to 275°F	350°F	325 to 350°F	350°F	350°F	350°F
Viscosity	900 cPs @ 250°F	900 cPs @ 350°F	1150 cPs @ 350°F	1000 cPs @ 350°F	1080 cPs @ 350°F	800 cPs @ 350°F
Gardner Color	1	1	1	2	1	1
Speed of Set	Fast	Fast	Medium Fast	Fast	Fast	Slow
Service Temperature Range	-40 to +140°F	-40 to +155°F	-40 to +155°F	0 to +170°F	-40 to +160°F	-40 to +155°F
Density	0.93	0.93	0.97	0.97	0.93	0.93

Note: Specifications are determined using standard laboratory tests based on ASTM test methods, and are subject to actual product technical data sheets.